20th Anniversary of KSDT

KISM 2022

Korean International Semiconductor Conference on Manufacturing Technology 2022

November 13-16, 2022 | Paradise Hotel Busan (Haeundae Beach), Busan, Korea

Session Title:	[WE1] Package Material/Unit Process
Session Date:	November 16 (Wed.), 2022
Session Time:	10:45-11:45
Session Room:	Room E (Grand Ballroom 3, 2F)
Session Chair:	Dr. Tae Ik Lee (KITECH, Korea)

[WE1-1] 10:45-11:05

Thermal Fatigue Life-Prediction of Microelectronics Package with Respect to Solder Type under Repeated Thermal Cycle Test

You-Gwon Kim, Heon-Su Kim (Hanyang Univ., Korea), Do-Hyeong Kim, Dong-Min Jang, Jin-Woo Jang, Seung-Yeoung Lee (Samsung Electronics Co., Ltd., Korea), and Hak-Sung Kim (Hanyang Univ., Korea)

[WE1-2] 11:05-11:25

Low-Temperature Dopant Activation of Mesa Structured Si for M3D Integration

Euyjin Park and Hyun-Yong Yu (Korea Univ., Korea)

[WE1-3] 11:25-11:45

Heterogenous Hybrid Inverter Using Monolithic 3D Integration

Sun Bum Kim, Chan Seul Lee, Se Hyeon Choi, Se Jin Kim, Chae Won Kim, and Changhwan Choi (Hanyang Univ., Korea)